

Technical Characteristics

	HGO	HG2	HG3	HG4
Number of contacts	5	12	19	33
Contact diameter	0.012 (0.30)	0.016 (0.40)	0.016 (0.40)	0.016 (0.40)

Materials

Body	Polyetherimide
Insulators	Liquid crystal polymer
Seals	Silicone

Contact Materials & Plating

	HC	MR
Sockets	Beryllium copper wires Brass body components Gold over nickel plating on mating surface Gold flash over nickel on termination	Beryllium copper clip Copper-zinc-lead body component Gold plating over Nickel underplating
Pins	Phosphor bronze Gold over nickel plated	

Terminations

Crimp (Pin & Socket)	26 to 28 AWG <i>Optional terminations, including solder cup and straight-dip pc tails (for panel mount receptacles), are special order only. Please contact factory for availability.</i>
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Shielding (Optional)

Effectiveness	Up to 3 GHz
Attenuation	50 dB maximum at 3 GHz

Mechanical

Mating cycle life	Up to 20,000 with Hyperboloid contact - Up to 2,000 with Flextac contact
Contact extraction force	0.50 to 1.60 oz. per contact

Electrical

Current Rating (A) <i>(per contact, with all contacts energized)</i>	5.5	3	2.5	1
Contact Resistance	< 8.0 mΩ			
Breakdown Voltage Between Contacts	1,000 V max.			
Dielectric Withstanding Voltage	1125 V			
Insulation Resistance	> 5x10 ⁴ MΩ at 500 VDC			

Physical & Environmental

Operating Temperature Rating	-40° to 125° C
Processing Temperature Range	Up to 185° C
Flammability	Materials meet the requirements of UL94 V-0
Sterilization	Steam Autoclave, EtO, Sterrad®2)
Fingerproofing	Meets IEC 60601-1 requirements
Sealing (mated condition)	IP65

Notes:

- 1) HyperGrip is patented under US patent numbers: 7,326,091B2; 7,661,995B2; D596,127S; 7,938,670; D615,932; D616,825
- 2) Sterrad® is a registered trademark of Advanced Sterilization Products (ASP) division of Ethicon US, LLC, a Johnson & Johnson Company.
Dimensions are in inches (mm)